

INTERNATIONAL STANDARD

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**Device embedded substrate –
Part 1-1: Generic specification – Test methods**

**Substrat avec appareil(s) intégré(s) –
Partie 1-1: Spécification générique – Méthodes d'essai**



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DEVICE EMBEDDED SUBSTRATE –

Part 1-1: Generic specification – Test methods

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The text of this standard is based on the following documents:

FDIS	Report on voting
91/1248/FDIS	91/1260/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62878, published under the general title *Device embedded substrate*, can be found on the IEC website.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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DEVICE EMBEDDED SUBSTRATE –

Part 1-1: Generic specification – Test methods

1 Scope

This part of IEC 62878 specifies the test methods of passive and active device embedded substrates. The basic test methods of printed wiring substrate materials and substrates themselves are specified in IEC 61189-3.

This part of IEC 62878 is applicable to device embedded substrates fabricated by use of organic base material, which include for example active or passive devices, discrete components formed in the fabrication process of electronic wiring board, and sheet formed components.

The IEC 62878 series neither applies to the re-distribution layer (RDL) nor to the electronic modules defined as an M-type business model in IEC 62421.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-2-1, *Environmental testing – Part 2-1: Tests – Test A: Cold*

IEC 60068-2-2, *Environmental testing – Part 2-2: Tests – Test B: Dry heat*

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61189-3, *Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 3: Test methods for interconnection structures (printed boards)*

IEC TS 62878-2-4:2015, *Device embedded substrate – Part 2-4 – Guidelines – Test element groups (TEG)*

3 Terms, definitions and abbreviations

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 apply.

3.2 Abbreviations

AABUS as agreed between user and supplier

AOI automated optical inspection

LSI large scale integration